



Material Content Data Sheet



Sales Product Name		BSZ021N04LS6		Issued		16. July 2019		
MA#		MA004017252						
Package		PG-TSDSON-8-26		Weight*		36.81 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.723	1.97	1.97	19654	19654
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		67	
	non noble metal	zinc	7440-66-6	0.010	0.03		267	
	non noble metal	iron	7439-89-6	0.197	0.53		5345	
wire	non noble metal	copper	7440-50-8	7.988	21.70	22.27	217015	222694
	noble metal	gold	7440-57-5	0.028	0.07	0.07	748	748
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		996
plastics	plastics	epoxy resin	-	1.888	5.13		51293	
	inorganic material	silicondioxide	60676-86-0	16.406	44.57	49.80	445700	497989
	leadfinish	non noble metal	tin	7440-31-5	0.395	1.07	1.07	10738
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	552	552
solder	non noble metal	tin	7440-31-5	0.020	0.05		532	
	noble metal	silver	7440-22-4	0.024	0.07		665	
	non noble metal	lead	7439-92-1	0.935	2.54	2.66	25407	26604
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001	0.00		34	
	non noble metal	zinc	7440-66-6	0.005	0.01		138	
	non noble metal	iron	7439-89-6	0.101	0.28		2751	
heatspreader	non noble metal	copper	7440-50-8	4.112	11.17	11.46	111720	114643
	inorganic material	phosphorus	7723-14-0	0.001	0.00		32	
	non noble metal	zinc	7440-66-6	0.005	0.01		128	
*deviation	non noble metal	iron	7439-89-6	0.094	0.26		2553	
	non noble metal	copper	7440-50-8	3.816	10.37	10.64	103665	106378
	Sum in total:						100.00	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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